

ABSTRACT

When a semiconductor chip is mounted on a mount
substrate by bonding bumps, bonding failure is caused by
5 misalignment between the bumps.

Before a semiconductor chip having a plurality of bumps
is mounted on a mount substrate (3) having a plurality of
bumps (4) by flip chip bonding, a resist layer (5) having a
thickness larger than that of the bumps (4) is formed on the
10 mount substrate (3) with the bumps. By patterning the
resist layer (5), projecting guides (5A) of semicircular
cross section are formed on the mount substrate (3) so as to
protrude near the bumps (4) and from a surface on which the
bumps (4) are provided, and to have guide faces (curved
15 faces) pointing toward the bumps (4).